

WHAT IS CLAIMED IS:

1. A method of manufacturing a member pattern having a patterned member on a substrate, comprising:
 - a first exposure step of exposing a desired
5 region of a negative type photosensitive material applied to the substrate to light from a first direction;
 - a second exposure step of exposing the desired
region of the negative type photosensitive material
10 to light from a second direction opposite to said first direction;
 - a development step of performing development after said exposure steps to form a precursor pattern of said member; and
15 a step of baking said precursor pattern.
2. The method of manufacturing a member pattern according to Claim 1, wherein said negative type photosensitive material is applied to extend over a
20 member previously disposed on said substrate and said substrate.
3. The method of manufacturing a member pattern according to Claim 2, wherein the member previously
25 disposed on said substrate has a higher optical reflectance than said substrate.

4. The method of manufacturing a member pattern according to Claim 2, wherein the member previously disposed on said substrate is a member that is formed in a process involving exposure, development and
5 baking of a photosensitive material.

5. The method of manufacturing a member pattern according to Claim 2, wherein the member previously disposed on said substrate has an overhanging part in
10 the cross section thereof.

6. The method of manufacturing a member pattern according to Claim 1, wherein said patterned member is an insulating member, and said insulating member
15 has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulating member interposed therebetween.

7. A method of manufacturing a member pattern
20 having a patterned member on a substrate, comprising:
a first exposure step of exposing a desired region of a negative type photosensitive material applied to the substrate to light from a first direction;
25 a development step of performing development after said first exposure step to form a precursor pattern of said member;

a second exposure step of exposing the precursor pattern of said member to light from a second direction opposite to said first direction; and

5 a step of baking said precursor pattern after said second exposure step.

8. The method of manufacturing a member pattern according to Claim 7, wherein said negative type
10 photosensitive material is applied to extend over a member previously disposed on said substrate and said substrate.

9. The method of manufacturing a member pattern
15 according to Claim 8, wherein the member previously disposed on said substrate has a higher optical reflectance than said substrate.

10. The method of manufacturing a member
20 pattern according to Claim 8, wherein the member previously disposed on said substrate is a member that is formed in a process involving exposure, development and baking of a photosensitive material.

25 11. The method of manufacturing a member pattern according to Claim 8, wherein the member previously disposed on said substrate has an

overhanging part in the cross section thereof.

12. The method of manufacturing a member
pattern according to Claim 7, wherein said patterned
5 member is an insulating member, and said insulating
member has a contact hole for electrically
interconnecting paired conductive members stacked on
said substrate with the insulating member interposed
therebetween.

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13. A method of manufacturing a wiring
structure having, on a substrate, a first wiring and
a second wiring intersecting said first wiring and
disposed over the first wiring through an insulator,
15 wherein a process of forming said insulator
comprises: a first exposure step of exposing a
desired region of a negative type photosensitive
insulating material to light from a first direction,
the negative type photosensitive insulating material
20 being applied to extend over said substrate and the
first wiring disposed on the substrate; a second
exposure step of exposing the desired region of the
negative type photosensitive insulating material to
light from a second direction opposite to said first
25 direction; a step of performing development after
said exposure steps to form a precursor pattern of
said insulator; and a step of baking the precursor

pattern of said insulator.

14. The method of manufacturing a wiring structure according to Claim 13, wherein said first
5 wiring is a member which has a higher optical reflectance than said substrate.

15. The method of manufacturing a wiring structure according to Claim 13, wherein said first
10 wiring is a member that is formed in a process involving exposure, development and baking of a photosensitive material.

16. The method of manufacturing a wiring
15 structure according to Claim 13, wherein said first wiring has an overhanging part in the cross section thereof.

17. The method of manufacturing a wiring
20 structure according to Claim 13, wherein said insulator has a contact hole for electrically interconnecting paired conductive members stacked on said substrate with the insulator interposed therebetween.

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18. A method of manufacturing an electron source having a wiring structure and an electron

emitting element connected to said wiring structure,
the wiring structure having, on a substrate, a first
wiring and a second wiring intersecting said first
wiring and disposed over the first wiring through an
5 insulator, wherein said wiring structure is
manufactured according to the method in Claim 13.

19. A method of manufacturing an image display
device having a wiring structure, an electron
10 emitting element connected to said wiring structure
and an image display member for displaying an image
by irradiation with electrons from said electron
emitting element, the wiring structure having, on a
substrate, a first wiring and a second wiring
15 intersecting said first wiring and disposed over the
first wiring through an insulator, wherein said
wiring structure is manufactured according to the
method in Claim 13.

20 20. A method of manufacturing a wiring
structure having, on a substrate, a first wiring and
a second wiring intersecting said first wiring and
disposed over the first wiring through an insulator,
wherein a process of forming said insulator
25 comprises: a first exposure step of exposing a
desired region of a negative type photosensitive
insulating material to light from a first direction,

the negative type photosensitive insulating material being applied to extend over said substrate and the first wiring disposed on the substrate; a step of performing development after said first exposure step
5 to form a precursor pattern of said insulator; a second exposure step of exposing the precursor pattern of said insulator to light from a second direction opposite to said first direction; and a step of baking the precursor pattern after said
10 second exposure step.

21. The method of manufacturing a wiring structure according to Claim 20, wherein said first wiring is a member which has a higher optical
15 reflectance than said substrate.

22. The method of manufacturing a wiring structure according to Claim 20, wherein said first wiring is a member that is formed in a process
20 involving exposure, development and baking of a photosensitive material.

23. The method of manufacturing a wiring structure according to Claim 20, wherein said first
25 wiring has an overhanging part in the cross section thereof.

24. The method of manufacturing a wiring structure according to Claim 20, wherein said insulator has a contact hole for electrically interconnecting paired conductive members stacked on
5 said substrate with the insulator interposed therebetween.

25. A method of manufacturing an electron source having a wiring structure and an electron
10 emitting element connected to said wiring structure, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the first wiring through an insulator, wherein said wiring structure is
15 manufactured according to the method in Claim 20.

26. A method of manufacturing an image display device having a wiring structure, an electron emitting element connected to said wiring structure
20 and an image display member for displaying an image by irradiation with electrons from said electron emitting element, the wiring structure having, on a substrate, a first wiring and a second wiring intersecting said first wiring and disposed over the
25 first wiring through an insulator, wherein said wiring structure is manufactured in the method according to Claim 20.